PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT

NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HSIN-CHIANG LIN	09/21/2011
WEN-LIANG TSENG	09/21/2011
CHIEH-LING CHANG	09/21/2011

RECEIVING PARTY DATA

Name:	ADVANCED OPTOELECTRONIC TECHNOLOGY, INC.
Street Address:	No. 13, Gongye 5th RD., Hsinchu Industrial Park,Hukou Shiang
City:	Hsinchu Hsien 303
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13290144

CORRESPONDENCE DATA

Fax Number: (909)978-6366
Phone: 9099786584
Email: Raymond.Chew@foxconn.com ,eoa-altis@foxconn.com,eoa-itec@foxconn.com,eoa-proce@foxconn.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.

Correspondent Name: Raymond J. Chew
Address Line 1:   288 South Mayo Avenue
Address Line 4:   City of Industry, CALIFORNIA 91789

ATTORNEY DOCKET NUMBER:	US38983

NAME OF SUBMITTER:	Raymond J. Chew

Total Attachments: 2
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PATENT

CH $40.00   13290144

ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

1.	HSIN-CHIANG LIN	, residing at	Hukou, Hsinchu, Taiwan
2.	WEN-LIANG TSENG	, residing at	Hukou, Hsinchu, Taiwan
3.	CHIEH-LING CHANG	, residing at	Hukou, Hsinchu, Taiwan
4.		, residing at	
5.		, residing at	
6.		, residing at	
7.		, residing at	
8.		, residing at	

hereby sell(s), assign(s) and transfer(s) unto: **ADVANCED OPTOELECTRONIC TECHNOLOGY, INC.** having a principal place of business at **No. 13, Gongye 5th Rd., Hsinchu Industrial Park, Hukou Shiang, Hsinchu Hsien 303, Taiwan, R.O.C.** hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as *MANUFACTURING METHOD FOR LED PACKAGE* for which the undersigned

[   ] previously executed --- Ser. No. _____ and filing date of _____
[x] is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

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1. _Hsin-chiang Lin_   _2011-9-21_
   HSIN-CHIANG LIN   Date

2. _Wen-Liang Tseng_   _2011-9-21_
   WEN-LIANG TSENG   Date

3. _CHIEH-LING CHANG_   _2011-9-21_
   CHIEH-LING CHANG   Date

4. _____   _____
                                    Date

5. _____   _____
                                    Date

6. _____   _____
                                    Date

7. _____   _____
                                    Date

8. _____   _____
                                    Date

9. _____   _____
                                    Date